Intel® SR2100 2U Server Chassis Technical Product Specification

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Enterprise Platforms and Services Division

Revision History

Date	Revision Number	Modifications
01/29/2001	0.9	Preliminary for review only.
02/02/2001	1.0	Initial release.

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The Intel® STL2 Server Board may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

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1. Introduction

This specification details the feature set of the Intel® SR2100 Server Chassis, an Advanced Technology Extended (ATX) compatible server chassis designed to support the Intel® STL2 Server Board.

SR2100 features include:

- 2U rack mount chassis
- 88 mm H x 480 mm W x 612 mm L with front bezel
- Four hot swap drive bays capable of supporting two 1-inch and two 1.6-inch SCSI hard disk drives
- Ultra2/Ultra160 SCSI backplane with SAF-TE supporting up to four Single Connector Attachment (SCA) drives
- A Peripheral Component Interconnect (PCI) riser card for use with the Intel® STL2 Server Board
- Two system cooling fans
- One power supply cage which supports two 275-Watt Server System Infrastructure (SSI) Thin Power Supply (TPS) modules in an optional 1+1 redundant configuration
- One 3.5-inch fixed drive bay
- One slim CD-ROM drive
- Chassis intrusion switch
- Sliding rail mount kit

1.1 Rail Mount Support

The SR2100 comes with a rail mount kit that is used to mount the chassis into a (19-inch wide X up to a 30-inch deep) server cabinet.

An optional front or center mounting kit is also available with brackets that allow the chassis to be mounted in either front or center mount relay racks, or regular server cabinets. The brackets can be attached at the front of the chassis for front mounting, or in the middle of the chassis for center mounting.

For mounting in a regular server cabinet, the front mount brackets are attached to the front of the chassis, and a set of rear support brackets are attached to the back end of the cabinet. This allows the weight of the server to be distributed evenly to prevent the mounting rails on the cabinet from bending.

1.2 Front Bezel Features

The black front bezel is made of molded plastic. When installed, its design allows for maximum airflow. By using light pipes, system status Light Emitting Diodes (LEDs), from the front panel attached to the chassis behind the front bezel, can be monitored with the front bezel in the closed position. The front bezel is easily installed or removed by using detachable mounting arms. When mounted to the chassis, the mounting arms allow the front bezel to swing down away from the front of the chassis giving access to the system's drives bays and front panel.

1.3 Chassis Security

At the chassis level, a variety of security options are provided.

- A key lock on the front bezel can be used to prevent access to the power, sleep, and reset buttons located on the front panel and to the system drive bays.
- An intrusion switch is provided, allowing server management software to detect the removal of the top cover.

1.3.1 Intrusion Alarm Cable

The top cover depresses an open momentary switch. It is cabled to the server board by a 22 AWG twisted pair, terminated with a 2-pin connector.

1.4 I/O Panel

All input/output connectors are located on the back of the chassis. An ATX 2.03 compatible cutout is provided for I/O shield installation. A metal I/O shield must be installed in the cutout in order to maintain Electromagnetic Interference (EMI) compliance levels. The I/O cutout dimensions are shown in Figure 1 below.

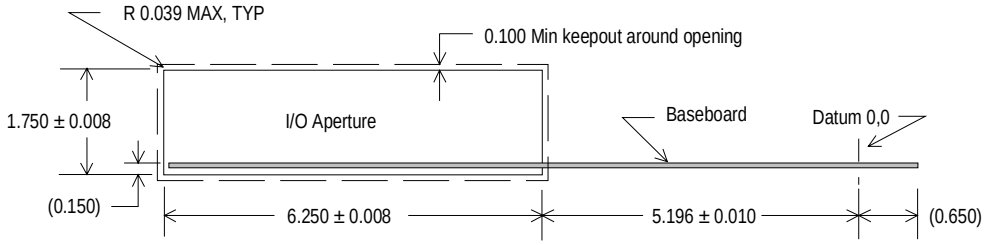

Figure 1. I/O Cutout Dimensions

1.5 Chassis Views

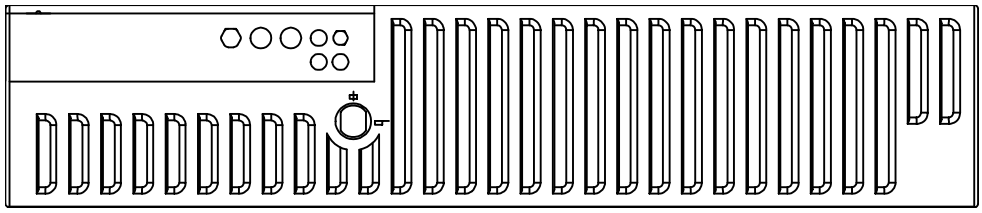

Figure 2. Front Chassis View, with Bezel

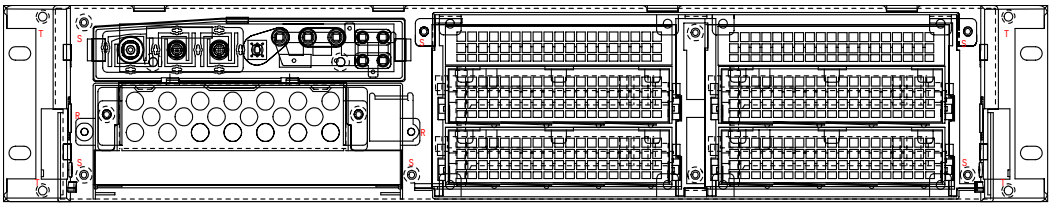

Figure 3. Front Chassis View, without Bezel

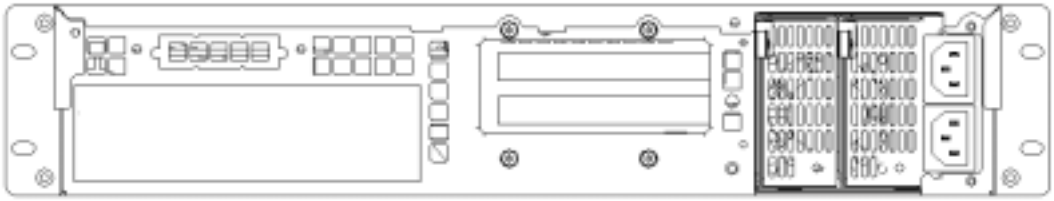

Figure 4. Rear Chassis View (1+1 Redundant Configuration)

1.6 Chassis Dimensions

Table 1. Chassis Dimensions

Height	80 mm
Width	480 mm
Depth	612 mm

2. Chassis Power Sub-system

The Intel® SR2100 Server Chassis power sub-system consists of the power enclosure and one or two 275-W SSI TPS modules. A remote enable feature is included which permits the chassis power to be activated from a variety of sources and allows the implementation of "Wake On LAN*" (WOL) or other remote management features.

The enclosure provides forced air-cooling for the modules, incorporates power distribution and an EMI filter capable of meeting the EMI requirements when two TPS modules are at full load.

The 275-W power supply module features Power Factor Correction (PFC), active load sharing capabilities and accepts AC input from an external EMI filter.

2.1 Power Supply/Chassis Configuration

The SR2100 server chassis can be configured with 1+0 single TPS module or 1+1 redundant TPS modules.

To ensure correct power monitoring when the SR2100 is configured with a single TPS module, it must be inserted in the left slot of the power cage (perspective is rear chassis view). In addition, when operating in the 1+0 configuration, use of the blank or "dummy" power supply module is required and the AC cord must be inserted in the top AC inlet.

With the addition of the optional second module for the 1+1 redundancy, the modules are hot-swappable and can be removed and replaced in the event of a failure. The system will remain in operation during a failed voltage condition and remain online during a module replacement for maximum up time. For correct functionality of the redundancy feature, each AC cord must be connected to a separate circuit.

The following table is a power supply input/output overview for both configurations.

Table 2. Power Supply Input/Output Summary

	275 Watt TPS	275 Watt 1+1 Redundant
+3.3 VDC Output	16 Amp Max	30.4 Amp Max
+5 VDC Output	19 Amp Max	36.1 Amp Max
+12 VDC Output	18 Amp Sustained	34.2 Amp Sustained
-12 VDC Output	0.5 Amp Max	0.5 Amp Max
+5 VDC Standby	1.5 Amp Max	1.5 Amp Max
Vbias	50 mA Max.	50 mA Max.
Output balancing	Total combined output power of all output shall not exceed 275 W.	Total combined output power of all output shall not exceed 510 W
AC Line Voltage	Auto ranging for either 100-127 VAC or 200-240 VAC	Auto ranging for either 100-127 VAC or 200-240 VAC
AC Line Frequency	50/60 Hz	50/60 Hz
AC Input Current	4.90 Amp at 115 VAC 2.45 Amp at 220 VAC	

2.2 Mechanical Outline of Power Supply

The approximate dimensions are: 82.2 mm high X 106 mm wide X 346.7 mm deep. The mechanical outline and dimensions are shown in Figure 5 below.

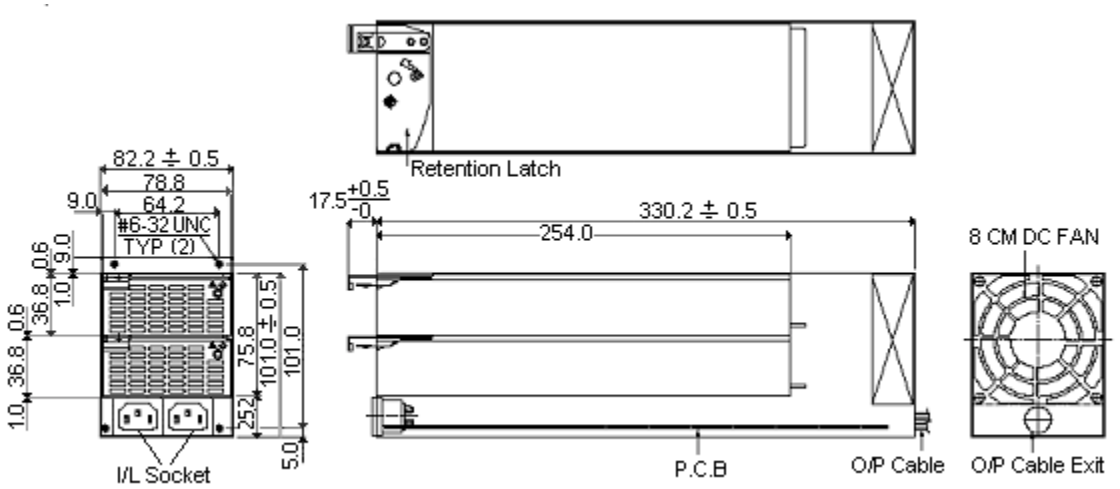

Figure 5. Outline Drawing Power System Enclosure

2.3 Power Connectors

The 24-pin Main power connector (P1) and the 10-pin SSI connector (P2) are used to provide power to the baseboard. The connector pinouts are shown in the following tables.

Table 3. P1 Main Connector Pin Assignments

Pin	Signal	18 AWG COLOR	Pin	Signal	18 AWG COLOR
1	+3.3 Vdc	Orange	13	+3.3 Vdc	Orange
2	+3.3 Vdc	Orange	14	-12 Vdc	Blue
3	GND	Black	15	GND	Black
4	+5 Vdc	Red	16	PS_ON#	Green
5	GND	Black	17	GND	Black
6	+5 Vdc	Red	18	GND	Black
7	GND	Black	19	GND	Black
8	PWR OK	Gray	20	Reserved	NC
9	5 VSB	Purple	21	+5 Vdc	Red
10	+12 Vdc	Yellow	22	+5 Vdc	Red
11	+12 Vdc	Yellow	23	+5 Vdc	Red
12	+3.3 Vdc	Orange	24	GND	Black

Note: The 5-V power and 5-V remote sense are double crimped into a single contact at pin 4. The remote sense return and GND are double crimped into a single contact at pin 5. Note the 12-V remote sense should be connected just before the 240 VA current sense resistors on the power share board.

Table 4. P2 SSI Connector Pin Assignments

Pin	Signal	Color	Pin	Signal	Color
1			6	Reserved	
2	Reserved		7	Reserved	
3	3.3-V Remote Sense	White/Brown Stripe	8	Reserved	
4	Reserved		9	I^2C Data	White/Green Stripe
5	Reserved		10	I^2C Clock	White/Yellow Stripe

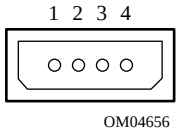

Figure 6. Peripheral Power Connector

The Hot-Swap Backplane power connector and peripheral power connector (P3/P4) are standard four-pin shrouded plastic PC power connectors with mechanical keying. Connector pinout is shown below.

Table 5. Peripheral Power Connector

PIN	Signal	18 AWG COLOR
1	+12 VIO	Yellow
2	GND	Black
3	GND	Black
4	+5 Vdc	Red

Table 6. P5 Floppy Power Connector

PIN	SIGNAL	22 AWG COLOR
1	+5 Vdc	Red
2	GND	Black
3	GND	Black
4	+12 VIO	Yellow

2.4 TPS Module Connector Pin Out

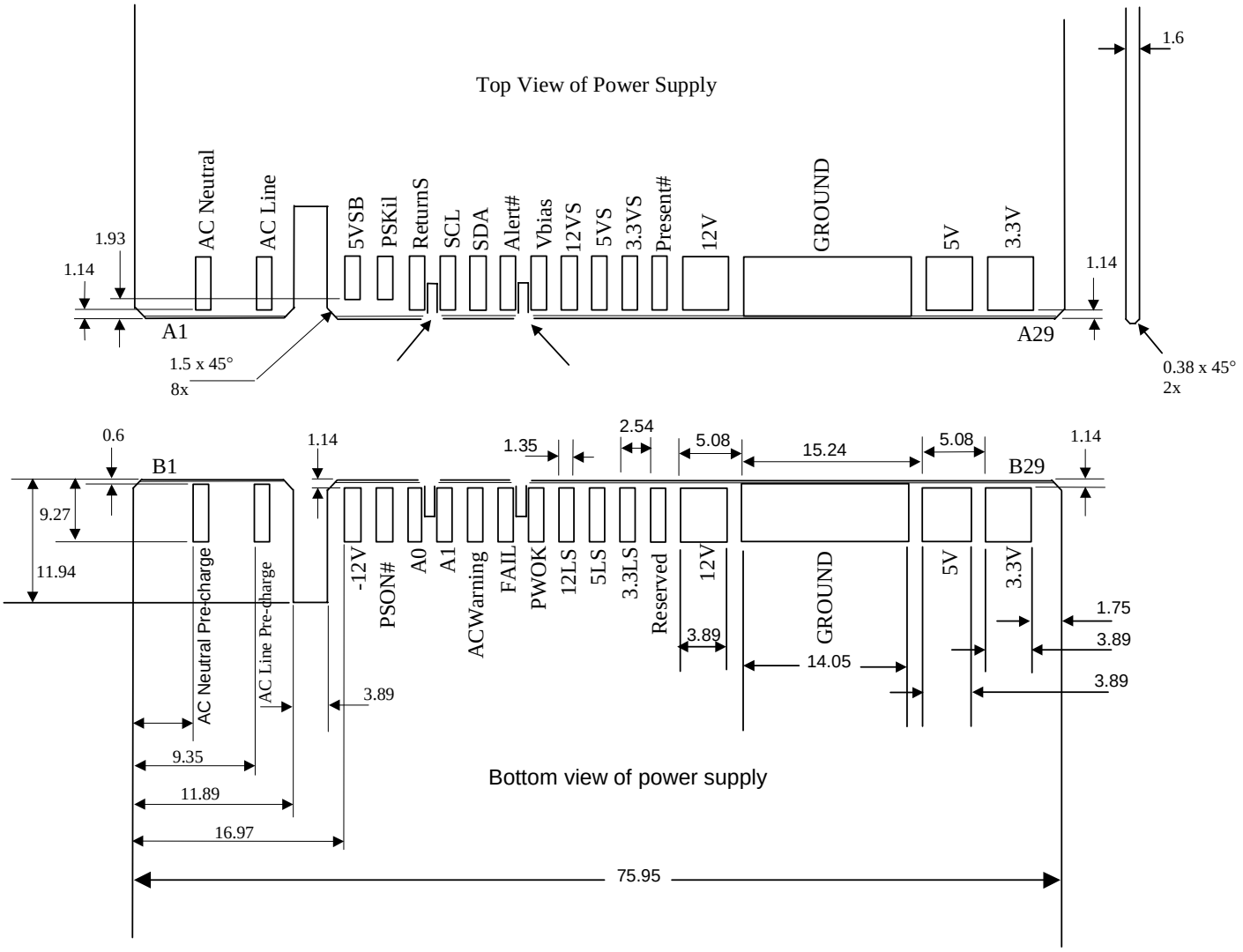

Figure 7. Power Supply Module Edge Connector

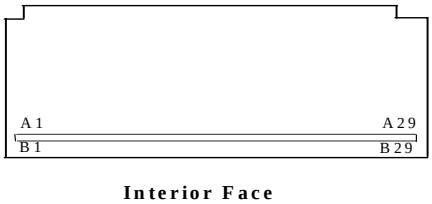

Figure 8. Module Connector Location

Table 7. Module Connector Pinout

Description	Pin#	Pin#	Description
NC	B1	A1	NC
AC Neutral Pre-charge	B2	A2	AC Neutral
NC	B3	A3	NC
AC Line Pre-charge	B4	A4	AC Line
NC	B5	A5	NC
NC	B6	A6	NC
-12 V	B7	A7	5 VSB
PSON#	B8	A8	PSKill
A0	B9	A9	ReturnS
A1	B10	A10	SCL
AC Warning	B11	A11	SDA
Fail	B12	A12	Alert#
PWOK	B13	A13	Vbias
12 LS	B14	A14	12 VS
5 LS	B15	A15	5 VS
3.3 LS	B16	A16	3.3 VS
Reserved	B17	A17	Present#
12 V	B18	A18	12 V
12 V	B19	A19	12 V
Ground	B20	A20	Ground
Ground	B21	A21	Ground
Ground	B22	A22	Ground
Ground	B23	A23	Ground
Ground	B24	A24	Ground
Ground	B25	A25	Ground
5 V	B26	A26	5 V
5 V	B27	A27	5 V
3.3 V	B28	A28	3.3V
3.3 V	B29	A29	3.3 V

3. Chassis Cooling

Two system fans, the power supply fan and processor fan(s) provide cooling for the system. Two 80-mm system fans are mounted in the middle of the chassis.

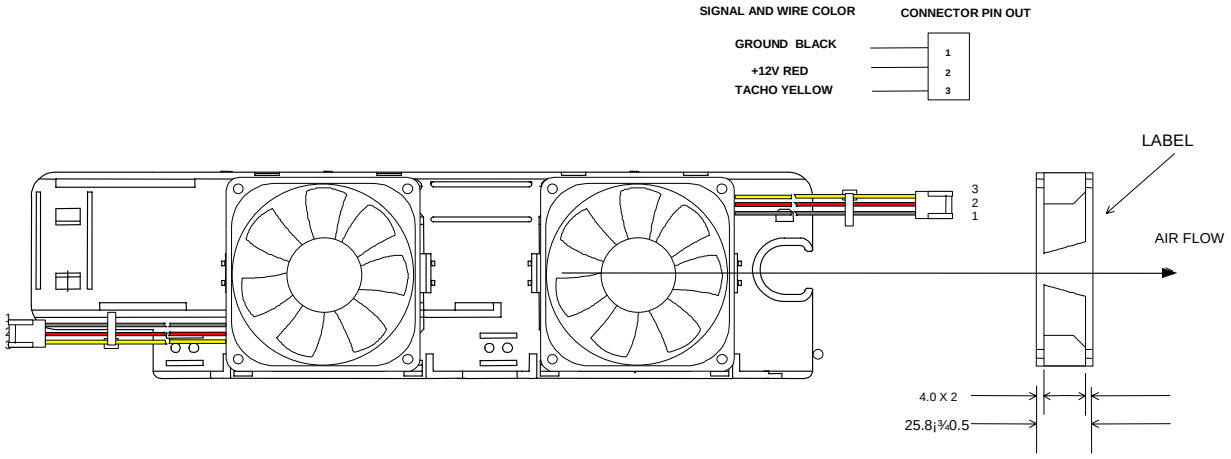

Figure 9. 80-mm Mid System Fan

The system fans are easily swapped out with the removal of the top cover. The system fans are not hot swappable. The server must be turned off before the fans can be replaced.

4. Chassis Peripheral Bays

4.1 3.5" Fixed Drive Bay

The chassis provides a 3.5-inch fixed drive bay that may be used for a standard floppy drive, a 1-inch hard disk drive, or other half height peripheral. The fixed drive bay is located directly above the slimline drive bay. Removal of the front bezel and top cover is required to install a device in the 3.5-inch drive bay.

4.2 Slim CD-ROM Drive Bay

The chassis provides a 0.5-inch (12.7 mm) fixed slimline bay for an Integrated Device Electronics (IDE) device, such as a CD-ROM or DVD-ROM drive. The fixed drive bay is located directly below the 3.5-inch drive bay. Removal of the front bezel and top cover is required to install a device in the slimline drive bay. A mounting tray is included with the chassis accessory kit.

4.3 Low Voltage Differential (LVD) SCSI Hot Swap Drive Bay

The Intel® SR2100 Server Chassis can support up to four 1-inch high or two 1-inch and two 1.6-inch high, 3.5-inch, SCA2, Ultra2/Ultra160 hard drives. The SCSI drive bay is accessible from the front of the chassis when the front panel is open. Four hard drive carriers are provided with the chassis to allow hard drives to be inserted or removed from the drive bay.

5. Universal Front Panel

The front panel is located behind the front bezel above the 3.5-inch fixed drive bay. The Universal Front Panel has four switches for system operation and seven LEDs to display the system's operating state.

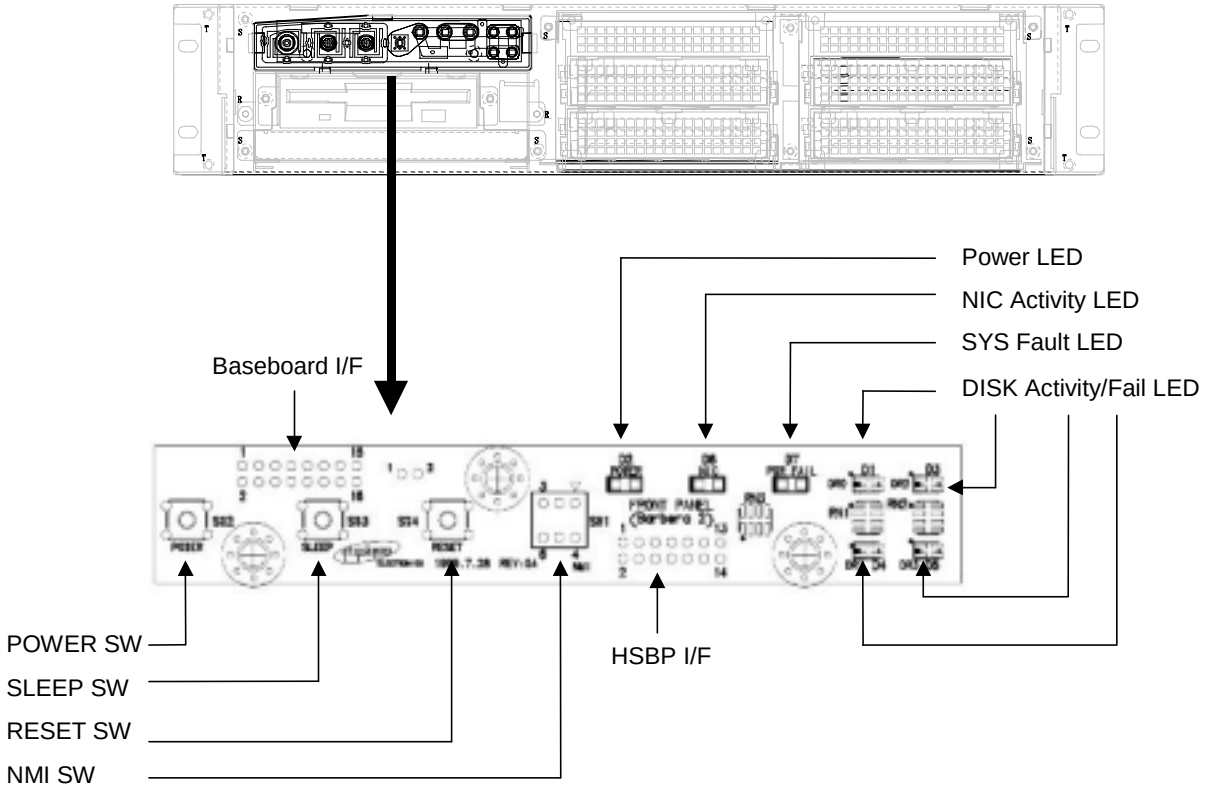

Figure 10. Front Panel and Functions

Table 8. Summary of Front Panel Features

	Function
Switches:	
Power	Toggle system power On/Off. Momentary push button switch, Advanced Configuration and Power Interface (ACPI) compliant
Sleep	Activate sleep mode. Momentary push button switch, ACPI compliant
Reset	Reset system. Momentary push button switch
Non-Maskable Interrupt (NMI)	Assert NMI to Server Board, Momentary push button switch.

LED Indicators:	Function	Color
Power	Indicates system power on, blinking green indicates system is in sleep mode	Green
Hard Drive Activity/Fault	Blinking green indicates hard drive activity. Yellow indicates drive failure.	Bicolor green/yellow.
Network Interface Card (NIC) activity	Indicates NIC activity	Green
SYS Fault	Indicates a power or fan failure	Yellow
Connectors:		
J2: Front panel to Intel® STL2 Server Board	SSI-compliant interconnect to the server board signals, passes I^2C information from Hot-Swap Backplane (HSBP) to server board.	
J3: Front panel to Hot Swap Backplane (HSBP)	Transfers drive activity and status indicators from backplane to front panel, provides I^2C status to front panel for transfer to server board.	

5.1 Switches

- The four switches control power-on, sleep mode, reset, and NMI.
- The NMI switch is accessible via a small hole in the front of the chassis and requires a small instrument to push it.

5.2 LED Indicators

- All LED's are Active Low.
- The current limiting resistors for the power, SYS fault LED, and NIC LED are implemented on the server board.
- The LEDs on the front panel shall be rated to 20 mA continuous current.
- Bicolor hard drive activity/fault LEDs shall be rated appropriately for the current limiting resistors implemented on the front panel.
- The green *NIC Activity LED* indicates Network link presence and activity.
- The yellow *SYS Fault LED* indicates a failure related to either a fan failure or a power supply fault.
- The bicolor yellow/green *DISK Activity/Fail LEDs* display hard drive activity for each hard drive when blinking green. They indicate a drive failure when continuously yellow.

5.2.1 Power LED

The Power LED is capable of showing three power related states; Solid on, Blinking 1Hz, and Blinking 3 Hz. The Baseboard Management Controller (BMC) interprets the state of 5-V Standby, 5 V, the Power State, and the PS-ON signal and drives the Power LED according to the following table.

Table 9. Power LED States

Power State	5-V Standby	PWR_GD	PS-ON	Power LED	Condition
ON	ON	ON	High	ON	Power ON and OK
ON	ON	OFF	High	FAST BLINK~3.3 Hz	Supply failed
ON	OFF	ON	High	OFF	5-V Standby failure
ON	OFF	OFF	High	OFF	AC Power has failed
OFF	OFF	ON	Low	OFF	5-V Standby failure
OFF	ON	OFF	Low	OFF	Normal Power OFF
OFF	OFF	OFF	n/a	OFF	Normal OFF & Unplugged
SLEEP	ON	ON	High	SLOW BLINK ~1 Hz	Machine is in S1 - S3 sleep state

5.2.2 SYS Fault LED

The Fault LED is NOT designed to detect all system faults. The purpose of the Fault LED is to alert the System Administrator that a power fault or fan failure has occurred. The BMC monitors whether the power supply is ON and operational using the **PWR_GD_PS** signal from the power supply. The controller uses the **PWR_GD_PS** signal to confirm whether the actual system power state matches the intended system on/off power state that was commanded using PS-ON. This signal generates an interrupt to the BMC, which it uses to detect loss of AC power. If AC power suddenly is lost, the BMC attempts to assert a system reset before the power is completely off. If the BMC asserts **PS-ON** and **PWR_GD_PS** does not become asserted, the BMC asserts the Fault LED signal on the front panel connector. It then continues to wait for the power supply to assert **PWR_GD_PS**; if the supply does eventually drive the signal, the BMC clears the power fault state and then proceeds to take the system out of reset.

5.2.3 Drive Fault LEDs

The four drive fault LEDs are controlled by the micro-controller on the hot swap back-plane and are used to indicate a failure status for each drive. A front panel interface connector is provided for an electrical path between the Hot-Swap SCSI Backplane and the drive status LEDs. During initialization, the micro-controller flashes the LEDs for 1 second as part of Power On Self Test (POST).

5.2.4 Connectors

- A 24-pin SSI connector provides control and status information to/from the Intel® STL2 Server Board.
- A 14-pin connector provides drive activity and fault status from the Hot Swap Backplane to the front panel, and provides I^2C data to the front panel.

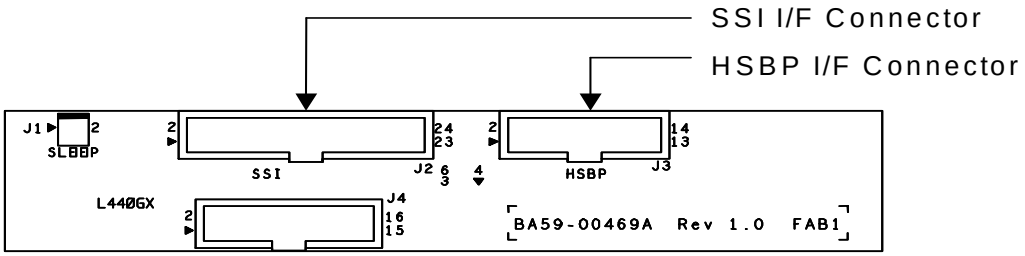

Figure 11. Connectors in Front Panel

The pin definitions in the following tables are classified by the following types.

Table 10. Pin Types

Type	Description
PWR	Power connection (power or ground)
I/O	Bi-directional signal
O	Output signal
I	Input signal
O/C	Open-collector output signal
O/D	Open-drain output signal

5.2.5 Front Panel Cable for the Intel® STL2 Server Board

A 24-pin flat cable is used to connect the STL2 and J2 connector of Universal Front Panel board. The function of the each signal is listed in the following table.

Table 11. Intel® STL2 Server Board / Front Panel Interface (J2)

Pin #	I/O	Description
1	I	+5-V Stand-by from STL2 (Power LED Anode)
2	-	NC
3	-	NC
4	-	+5-V Stand-by from STL2 (Power/Fan Failure Anode)
5	I	Power LED Cathode
6	I	Fan-failure Cathode
7	-	NC
8	-	NC
9	-	NC
10	I	Power failure Cathode
11	O	Power Switch=Open Collector Low True
12	I	+3-V (NIC Activity LED Anode)
13	PWR	GND
14	I	NIC Activity LED Cathode

Pin #	I/O	Description
15	O	Reset Switch=Open Collector Low True
16	I/O	I^2C_SDA
17	PWR	GND
18	I/O	I^2C_SCL
19	O	Sleep Switch=Open Collector Low True
20	-	NC
21	PWR	Sleep Switch GND
22	-	NC
23	O	NMI Switch=Open Collector Low True
24	-	NC

5.2.6 I^2C, Front Panel to Hot-swap Backplane Cable

A 14-pin connector cables connect the Front Panel board to the Hot-Swap Backplanes to transfer the drive activities to LED indicators and provide the Intelligent Management Bus (IMB) bus path. The functions of the each signal are in the following table.

Table 12. HSBP / Front Panel Interface (J3)

Pin #	I/O	Description
1	I/O	I^2C SCL (Serial Clock)
2	PWR	GND
3	PWR	+5 V
4	I/O	I^2C SDA (Serial Data)
5	-	NC
6	-	NC
7	I	Drive0 Fault LED Cathode
8	I	Drive0 Activity LED Cathode
9	I	Drive1 Fault LED Cathode
10	I	Drive1 Activity LED Cathode
11	I	Drive2 Fault LED Cathode
12	I	Drive2 Activity LED Cathode
13	I	Drive3 Fault LED Cathode
14	I	Drive3 Activity LED Cathode

6. Hot-Swap SCSI Sub-System

The Hot-swap SCSI Sub-System supports the following features:

- Hot swapping of SCSI drives, that allows connection of SCSI devices while the power is on.
- Enclosure management and monitoring functions conforming to the *SCSI-Accessed Fault-Tolerant Enclosure Specification (SAF-TE)*, Revision 1.00.
- Full dual mode LVD/ Single Ended (SE) operation, compliant with Fast, Ultra, Ultra-2 and Ultra-160 SCSI bus operation.

6.1 Sub-System Purpose

The SR2100 server chassis Hot-Swap SCSI Backplane performs the tasks associated with hot-swappable SCSI drives.

6.1.1 Minimum Design Goals

The SR2100 Hot-Swap SCSI Backplane is designed to provide at least the following:

1. Four SCA2 connectors for four SCA2 compatible SCSI drives
2. Active termination on SCSI bus (SCSI-3 compatible)
3. Per-drive power control, including automatic slot power down upon drive removal

6.2 Abstract

The SR2100 Hot-Swap SCSI Backplane is made up of the following functional blocks:

- SCSI Bus with SCA (Single Connector Attach) drive connectors, and active terminators
- SCSI drive power control
- Configuration jumpers

6.3 Hot-Swap Backplane Board Layout

The Hot-Swap SCSI Backplane resides in the hot-swap drive bay of the SR2100 server chassis.

The following diagrams show the layout of components and connectors on the Hot-Swap SCSI Backplane printed circuit board. The ovals in the diagram below represent ventilation holes for the hard drive bay.

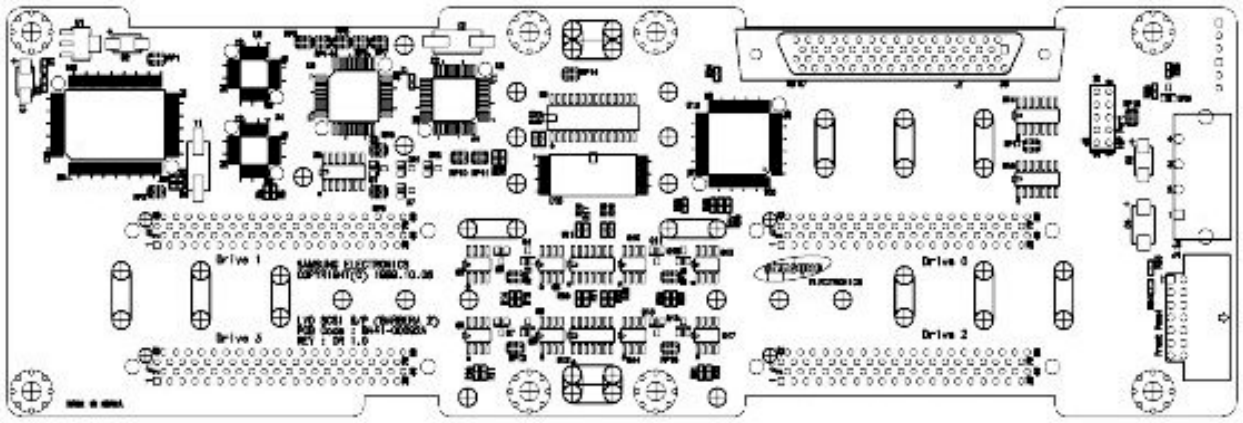

Figure 12. Hot-Swap SCSI Backplane – Component Side

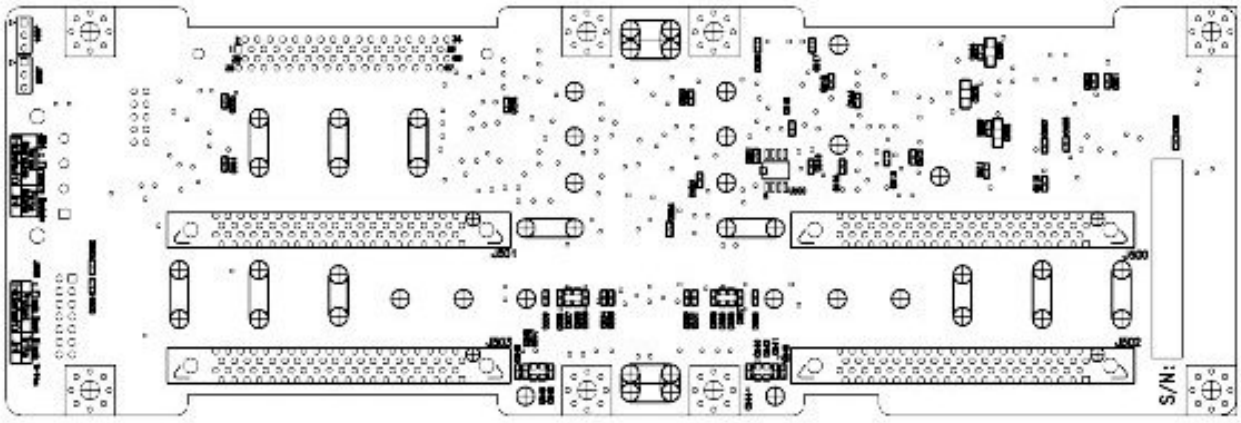

Figure 13. Hot-Swap SCSI Backplane – SCA2 Connector Side

6.3.1 Configuration Options

The following table describes the various configuration options on the SR2100 Hot-Swap SCSI Backplane, along with their function and intended usage.

Table 13. HSBP Configuration Jumpers

Option	Location	Description
Firmware Update	J504	Placing this jumper in the “FORCE UPDATE” position forces external firmware update of the program code stored in Flash memory. Placing this jumper in the “NORMAL OPERATION” position allows normal operation.
Flash Boot Block Write	J505	This jumper allows the boot block of the program flash to be updated. “PROTECT” (default) does not allow the boot block to be written to. “WRITE”, allows updating of the boot block.

6.4 Functional Description

This section defines the architecture of the SR2100 Hot-swap SCSI Backplane, including a description of functional blocks and how they operate. The following figure shows the functional blocks of the Hot-Swap SCSI Backplane.

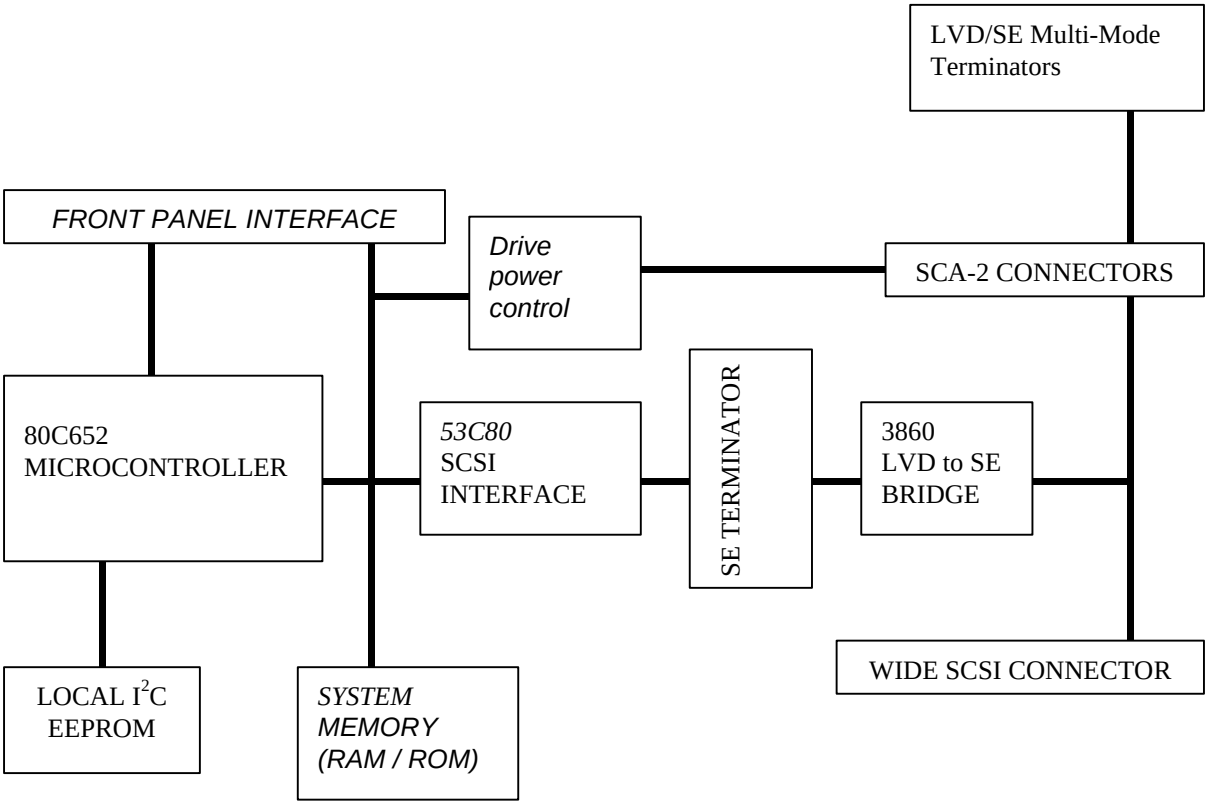

Figure 14. HSBP Functional Block Diagram

6.4.1 SCA2 Hot-Swap Connectors

The SR2100 Hot-Swap SCSI Backplane provides four hot-swap SCA2 connectors, which provide power and SCSI signals using a single connector. Each SCA drive attaches to the backplane using one of these connectors.

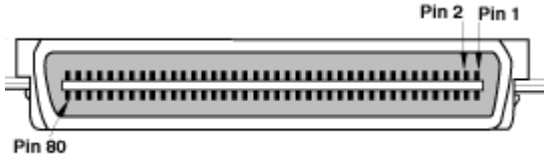

Figure 15. 80-Pin SCA2 Connector

6.4.2 Baseboard to SCSI Devices

A 68-pin SCSI cable is used to interface the SCSI backplane with the on-board SCSI channels of the Intel® STL2 Server Board or any add-in PCI SCSI or SCSI RAID controller installed on the PCI riser card. Four SCA2 connectors provide the interface between the Hot-Swap SCSI Backplane and hot-swap SCSI devices.

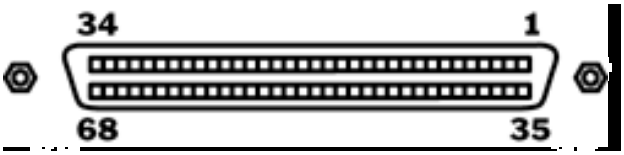

Figure 16. 68-Pin SCSI Cable Connector

Table 14. Ultra Wide (SE) and Ultra2 (LVD) SCSI Connector Pinout

Pin	Name	Pin	Name	Pin	Name	Pin	Name
1	+DB(12)	18	TERMPWR	35	-DB(12)	52	TERMPWR
2	+DB(13)	19	RESERVED	36	-DB(13)	53	RESERVED
3	+DB(14)	20	GROUND	37	-DB(14)	54	GROUND
4	+DB(15)	21	+ATN	38	-DB(15)	55	-ATN
5	+DB(P1)	22	GROUND	39	-DB(P1)	56	GROUND
6	+DB(0)	23	+BSY	40	-DB(0)	57	-BSY
7	+DB(1)	24	+ACK	41	-DB(1)	58	-ACK
8	+DB(2)	25	+RST	42	-DB(2)	59	-RST
9	+DB(3)	26	+MSG	43	-DB(3)	60	-MSG
10	+DB(4)	27	+SEL	44	-DB(4)	61	-SEL
11	+DB(5)	28	+C/D	45	-DB(5)	62	-C/D
12	+DB(6)	29	+REQ	46	-DB(6)	63	-REQ
13	+DB(7)	30	+I/O	47	-DB(7)	64	-I/O
14	+DB(P)	31	+DB(8)	48	-DB(P)	65	-DB(8)
15	GROUND	32	+DB(9)	49	GROUND	66	-DB(9)
16	DIFFSENS	33	+DB(10)	50	GROUND	67	-DB(10)
17	TERMPWR	34	+DB(11)	51	TERMPWR	68	-DB(11)

6.4.3 SCSI Interface

The SCSI interface on the SR2100 Hot-Swap SCSI Backplane provides the required circuitry between the SCSI bus and the 80C652 micro-controller. This allows the micro-controller to respond as a SCSI target. The interface consists of a Symbios* 53C80S SCSI Interface Chip, which functions as translator between the SCSI bus and the micro-controller. The 53C80S is a single-ended, narrow device.

6.4.4 LVD to SE Bridge

Since the 53C80S is a single-ended, narrow device, an Adaptec* AIC-3860 LVD-to-SE Transceiver (Bridge) is used to create a single-ended extension of the LVD bus. This allows the 53C80S to communicate with the LVD bus.

6.4.5 SE Termination

Passive SE termination is used for the single-ended extension of the SCSI bus that includes the 53C80S.

6.4.6 LVD/SE Multi-Mode Active SCSI Termination

The SCSI active terminators provide SCSI-3 compliant active termination for the backplane end of the SCSI bus. It is assumed that the other end of the SCSI segment is properly terminated as required by the SCSI-3 specification. Multi-mode termination is implemented on the SR2100 Hot-Swap SCSI Backplane using two Unitrode* UCC5638 Multi-mode SCSI 15 line terminators.

6.4.7 Power Control

As per the *SCSI-Accessed Fault-Tolerant Enclosure Specification* (SAF-TE), Revision 1.00, the power control on the SR2100 Hot-swap SCSI Backplane supports the following features:

- If supported, a SCSI or RAID controller will power down a drive when failure is detected and reported (using enclosure services messages) via the SCSI bus. This decreases the likelihood that the drive, which may be under warranty, is damaged during removal from the hot-swap drive bay. When a new drive is inserted, the power control waits a small amount of time for the drive to be fully seated, and then applies power to the drive in preparation for operation.
- If system power is on, the Hot-Swap SCSI Backplane immediately powers off a drive slot when it detects that a drive has been removed. This prevents possible damage to the drive when it is partially removed and re-inserted while full power is available. It also prevents disruption of the entire SCSI array from possible sags in supply voltage and resultant current spikes.
- Spare drives are kept in the hot-swap bay, but are left un-powered until a drive is determined to have failed. In this case, the hot spare can be powered up and put into service automatically without requiring immediate operator intervention to replace the drive.
- The Hot-Swap SCSI Backplane will automatically bypass the power control circuitry if a shorted drive is inserted or if a drive develops a short during operation. This prevents the Hot-Swap SCSI Backplane from being damaged by a drive that draws excessive current.

6.4.8 Micro-controller and Memory

The micro-controller provides the intelligence for the SR2100 Hot-Swap SCSI Backplane. It is implemented with a Phillips* 80C652 micro-controller, with a built-in I^2C interface. The micro-controller uses a 2-Mbit FLASH EEPROM for program code storage, and a 32-KB SRAM for program execution.

6.4.9 Front Panel Drive Fault LEDs

The Drive Fault Indicators are not physically part of the SR2100 Hot-Swap SCSI Backplane, but rather located on the system front panel. They are referenced here because the driving circuitry is entirely contained on the backplane. The drive fault LEDs are activated by the micro-controller, and indicate a failure status for each drive. A front panel interface connector is provided for an electrical path between the Hot-Swap SCSI Backplane, drive fault LEDs, and

front panel drive activity indication. During initialization, the micro-controller flashes the LEDs for 1 second as part of the POST.

6.4.10 IMB Bus

The IMB bus is a system-wide server management bus, based on the Phillips* I^2C bus specification. It provides a way for various system components to communicate independently of the standard system interfaces (e.g., PCI bus or processor/memory bus). The I^2C bus controller is integrated into the micro-controller. IMB connectivity is provided to the backplane via the front panel connector.

6.4.11 Local I^2C EEPROM and Temperature Sensor

An I^2C bus temperature sensor is connected to the micro-controller on a Private* I^2C bus. Micro-controller programming implements the private I^2C connection by explicitly setting and clearing appropriate clock and data signals, to emulate an I^2C-like interface to the sensor. Temperature information is made available to other devices in the chassis using Enclosure Services messages. A Dallas* DS1624 Serial EEPROM/Temperature Sensor implements this function. The EEPROM stores the Field Replaceable Unit (FRU) information for the backplane.

7. PCI-Riser Card

7.1 Riser Card for the Intel® STL2 Server Board

The Riser Card for STL2 provides the following feature sets:

- One 32-bit/33-MHz PCI slot
- One 64-bit/66-MHz PCI slot
- PCI 2.2 compatible

The PCI riser card for the STL2 is a dual bus riser card. It has two separate edge connectors occupying two PCI slots of the baseboard. Each of the two STL2 PCI slots is located on a separate PCI bus. The outer connector is attached to the riser by use of a flex circuit and is used for connecting to the 64-bit/66-MHz PCI slot on the STL2. The standard edge connector is inserted into the 32-bit/33-MHz PCI slot on STL2.

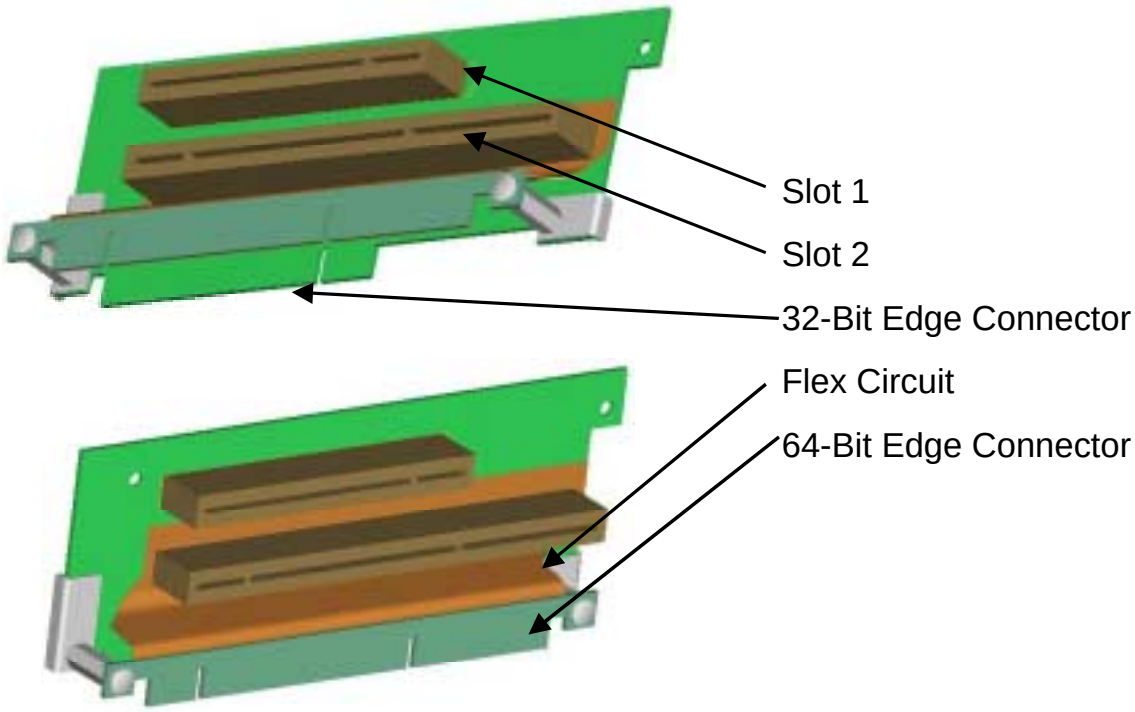

Figure 17. PCI Riser for STL2 Component and Connector Description

7.1.1 32 Bit PCI Edge Connector

This connector supports 5-V/32-bit feature and is inserted into PCI Slot 1 of Intel® STL2 Server Board.

7.1.2 64 Bit PCI Edge Connector

This connector supports 3.3-V/64-bit feature and is inserted into PCI Slot 2 of the STL2.

7.1.3 Slot 1 (Upper Slot)

This is a direct connect to PCI Slot 1 of the STL2. It provides support for 5-V/32-Bit/33-MHz PCI add-in cards.

7.1.4 Slot 2 (Lower Slot)

This is a direct connect to PCI Slot 2 of the Intel® STL2 Server Board. It provides support for 3.3-V/64-Bit/66-MHz PCI add-in cards. It is also capable of supporting “Universal” 32-bit PCI cards. Universal PCI cards are capable of supporting both 3.3 V and 5 V and have an edge connector capable of fitting into either a 5 V or 3.3 V only PCI slot.

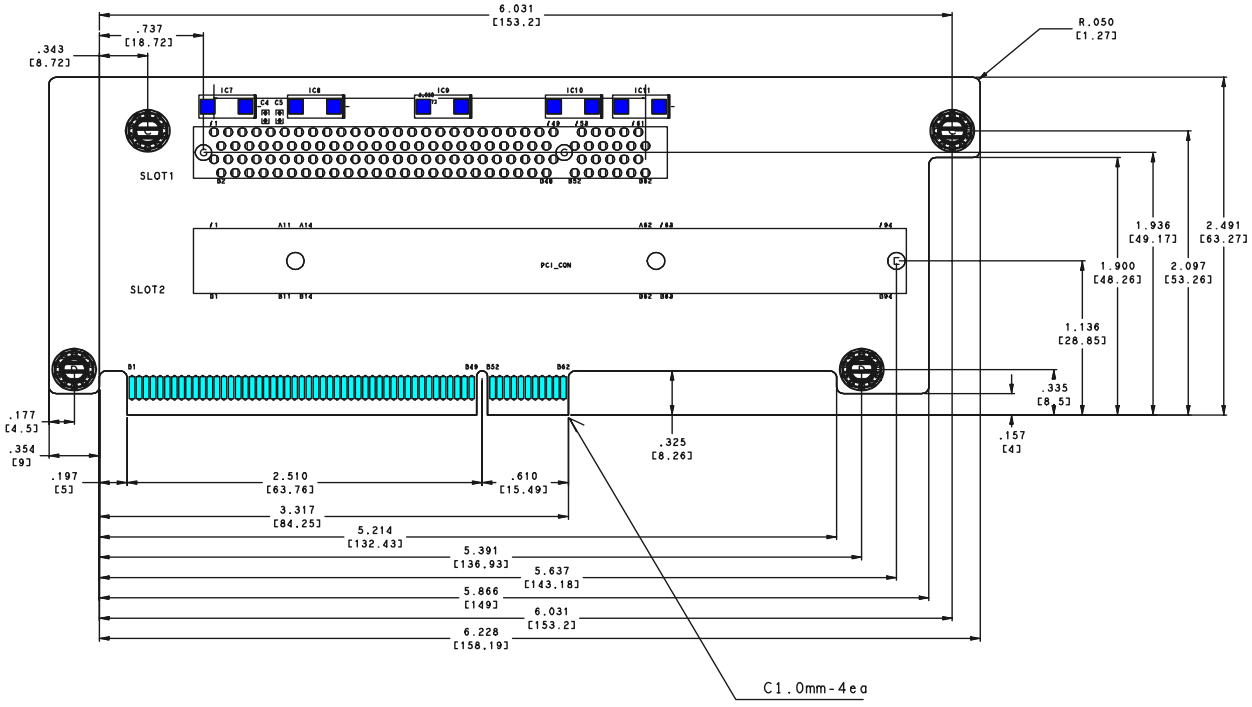

Figure 18. Component and Connector Placement of Rigid Printed Circuit

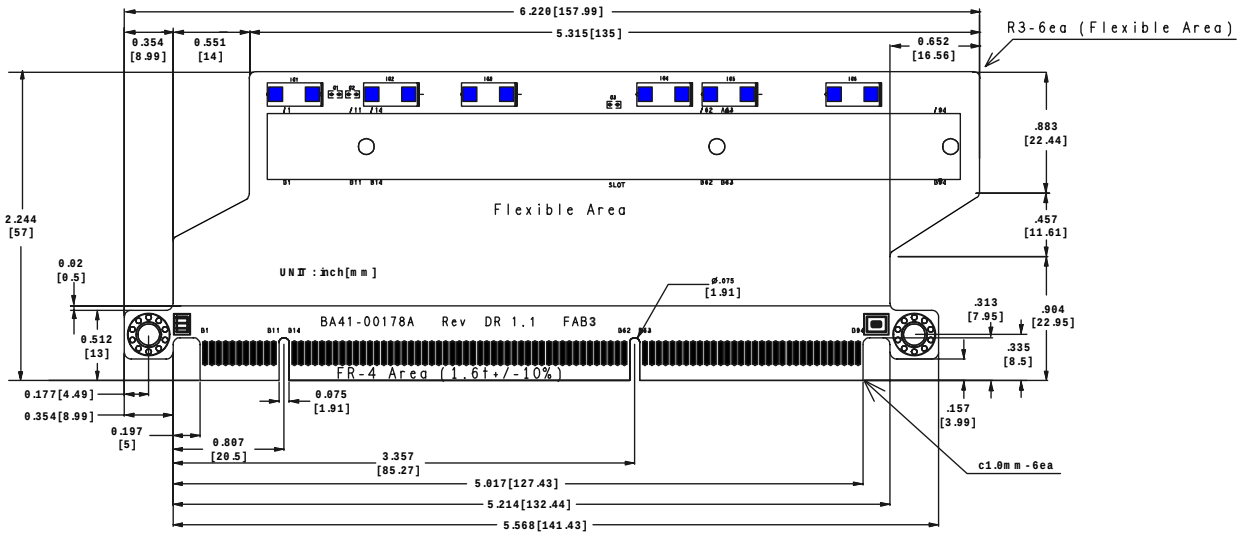

Figure 19. Component and Connector Placement of Flexible Printed Circuit

8. Intel® STL2 Server Board

The following is a summary of the feature set for the Intel® STL2 Server Board supported in the SR2100 server chassis. Please refer to the *Intel® STL2 Server Board Technical Product Specification* for additional details.

- Dual Intel® Pentium® III processor support.
  - Support for one or two identical Intel® Pentium® III processors for the PGA370 socket, which utilizes a new package technology called the Flip Chip Pin Grid Array (FC-PGA) package.
  - One embedded Voltage Regulating Modules (VRM) for support of the primary processor, and one VRM connector for support of the secondary processor.
- ServerWorks* ServerSet* III LE chipset.
  - 133-MHz Front Side Bus Capability.
  - NB6635 North Bridge 3.0 LE.
  - IB6566 South Bridge.
- Support for four JEDEC PC133 specification-compliant, 3.3-V, registered ECC SDRAM DIMMs.
  - Support for DIMM sizes 64 MB to 1 GB. Four DIMM slots allow a maximum installed memory of 4 GB.
  - ECC single-bit correction, and multiple-bit detection.
- 64-bit, 66-MHz, 3.3-V keyed PCI segment with two expansion connectors and one embedded device.
  - Two 64-bit, 66-MHz, 3.3-V keyed PCI expansion slots.
  - Integrated onboard Adaptec* AIC7899 PCI dual-port SCSI controller providing separate Ultra-160/M and Ultra Wide SCSI channels.
- 32-bit, 33-MHz, 5-V keyed PCI segment with four expansion connectors and two embedded devices.
  - Four 32-bit, 33-MHz, 5-V keyed PCI expansion slots.
  - Integrated onboard Intel® EtherExpress™ PRO100+ 10/100-Mbit PCI Ethernet controller (Intel® 82559) with an RJ-45 Ethernet connector.
  - Integrated onboard ATI Rage* IIC video controller with 4 MB of onboard SGRAM video memory.
- Compatibility bus segment with three embedded devices.
  - Super I/O Controller (PC97317) providing all PC-compatible I/O (floppy, parallel, serial, keyboard, mouse, and Real Time Clock).
  - Baseboard Management Controller (BMC) (DS80CH11) providing monitoring, alerting, and logging of critical system information including thermal, voltage, fan, and chassis intrusion information obtained from embedded sensors on the server board.
  - 8-MB Flash device for system BIOS. Dual Universal Serial Bus (USB) ports.
- One IDE connector.
- Flash BIOS support for all of the above.
- Extended ATX board form factor (12-inches x 13-inches).

9. Product Safety and Regulations

CAUTION: This product is considered a professional product and only technically qualified persons or technically qualified assemblers of Intel® Identified Subassemblies / Products are intended to service and/or access inside the product.

9.1 Safety Precautions

Before you Begin

Only a technically qualified person shall access, integrate, configure and service this product.

Use Only for Intended Applications

- This product was evaluated as Information Technology Equipment (ITE) that may be installed in offices, schools, computer rooms and similar commercial type locations. The suitability of this product for other Product Categories and Environments other than an ITE application, such as medical, industrial, alarm systems, and test equipment, may require further evaluation.
- When you access this product for servicing, observe all warnings and cautions in this Guide.
- To avoid injury, be careful of:
  - Sharp pins on connectors
  - Sharp pins on printed circuit assemblies
  - Rough edges and sharp corners on the chassis
  - Hot components (i.e.: processors, voltage regulators, and heat sinks)
  - Damage to wires that could cause a short circuit
  - Other safety Caution noted in this guide

9.1.1 Before You Remove the Access Cover

The following Safety Cautions apply whenever you remove the access cover to access inside this product.

- Turn off all peripheral devices connected to this product.
- Turn off the server power by pressing the power button on the front of the product.
- Disconnect the AC power by unplugging all AC power cords from the chassis or wall outlet.
- Disconnect and label all cables and all telecommunication lines that are connected to I/O connectors or ports of this product.
- Provide some Electrostatic Discharge (ESD) protection by wearing an antistatic wrist strap attached to chassis ground—any unpainted metal surface—when handling components.

Retain all screws or other fasteners when removing access cover(s). Re-fasten access cover with original screws when work inside the product is complete.

CAUTION

- The power button on the front panel DOES NOT turn off the AC power. To remove power from the server, you must unplug the AC power cord from the wall outlet or the chassis.
- Hazardous electrical conditions may be present on power, telephone, and communication cables. Turn off the power and disconnect all AC power cords, telecommunications and networks connections attached to the server before opening it. Otherwise, personal injury or equipment damage can result.
- Hazardous voltage, current, and energy levels are present inside the power supply. There are no user-serviceable parts inside it. Refer all servicing to technically qualified service personnel.

9.1.2 Checking the Power Cords

WARNING

- Do not attempt to modify or use supplied AC power cords if they are not the exact type required.
- The power supply cords are the main disconnect device to mains (AC power). The socket outlet shall be installed near the equipment and shall be readily accessible
- If a power cord supplied with the chassis is not compatible with the AC wall outlet in your region, get one that meets the following criteria:
  - The cord must be rated for the available AC voltage and have a current rating that is at least 125 % of the current rating of the server.
  - The connector that plugs into the wall outlet must be a grounding-type male plug designed for use in your region. It must have certification marks showing certification by an agency acceptable in your region.
  - The connector that plugs into the AC receptacle on the power supply must be an IEC 320, sheet C13, type female connector.
  - In Europe, the cord must be less than 4.5 meters (14.76 feet) long, and it must be flexible <HAR> (harmonized) or VDE certified cordage to comply with the chassis' safety certifications.

9.1.3 Lithium Battery Replacement

CAUTION

Refer to technically qualified persons only for replacement of battery.

The following warning is provided on the server board configuration label, which is provided with the Intel server board boxed product. There is insufficient space on the server board to place this label. Therefore, the label must be placed permanently on the inside of the chassis, as close to the battery as possible.

WARNING

Danger of explosion if battery is incorrectly replaced.

Replace with only the same or equivalent type recommended by the manufacturer. Dispose of used batteries according to the manufacturer's instructions.

ADVARSEL!

Lithiumbatteri - Eksplosionsfare ved fejlagtig håndtering.

Udskiftning må kun ske med batteri af samme fabrikat og type. Levér det brugte batteri tilbage til leverandøren.

ADVARSEL!

Lithiumbatteri - Eksplosjonsfare.

Ved utskifting benyttes kun batteri som anbefalt av apparatfabrikanten. Brukt batteri returneres apparatleverandøren.

VARNING

Explosionsfara vid felaktigt batteribyte. Använd samma batterityp eller en ekvivalent typ som rekommenderas av apparattillverkaren. Kassera använt batteri enligt fabrikantens instruktion.

VAROITUS

Paristo voi räjähtää, jos se on virheellisesti asennettu.

Vaihda paristo ainoastaan laitevalmistajan suosittelemaan tyyppiin. Hävitä käytetty paristo valmistajan ohjeiden mukaisesti.

9.1.4 Equipment Rack Precautions

WARNINGS

- **ANCHOR THE EQUIPMENT RACK**: The equipment rack must be anchored to an unmovable support to prevent it from falling over when one or more servers are extended in front of it on slide assemblies. The equipment rack must be installed according to the manufacturer's instructions. The anchors must be able to withstand a force of up to 113 kg (250 lbs). You must also consider the weight of any other device installed in the rack.

- **MAIN AC POWER DISCONNECT**: You are responsible for installing an AC power disconnect for the entire rack unit. This main disconnect must be readily accessible, and it must be labeled as controlling power to the entire unit, not just to the server(s).
- **GROUNDING THE RACK INSTALLATION**: To avoid the potential for an electrical shock hazard, you must include a third wire safety-grounding conductor with the rack installation. If server power cords are plugged into AC outlets that are part of the rack, then you must provide proper grounding for the rack itself. If server power cords are plugged into wall AC outlets, the safety-grounding conductor in each power cord provides proper grounding only for the server. You must provide additional, proper grounding for the rack and other devices installed in it.
- **OVER CURRENT PROTECTION**: The server is designed for an AC line voltage source with up to 20 amperes of over current protection. If the power system for the equipment rack is installed on a branch circuit with more than 20 amperes of protection, you must provide supplemental protection for the server. If more than one server is installed in the rack, the power source for each server must be from a separate branch circuit. The overall current rating of a server configured with three power supplies is less than 12 amperes.

⚠ CAUTION

- **Temperature:** The operating temperature of the server, when installed in an equipment rack, must not go below 5 °C (41 °F) or rise above 35 °C (95 °F). Extreme fluctuations in temperature can cause a variety of problems in your server.
- **Ventilation:** The equipment rack must provide sufficient airflow to the front of the server to maintain proper cooling. It must also include ventilation sufficient to exhaust a maximum of 4,100 BTUs per hour for the server. The rack selected and the ventilation provided must be suitable to the environment in which the server will be used.

⚠ CAUTION

Integration of the SR2100 subassembly is a regulated activity: you must adhere to the assembly instructions in the SR2100 guide to ensure and maintain compliance with existing product regulations. Use only the described, regulated components specified in the SR2100 guide. Use of other products / components will void the UL listing of the product, will most likely void other compliance markings provided, and may result in noncompliance with product regulations in the region(s) in which the product is sold.

9.1.5 Do Not Overload Power

Do not overload the power supply output. To avoid overloading the power supply, make sure that the calculated total current load of all the modules within the computer is less than the maximum output current rating of the power supply. If you do not do this, the power supply may overheat, catch fire, or damage the insulation that separates hazardous AC line circuitry from low voltage user accessible circuitry and result in a shock hazard. If the load drawn by a module cannot be determined by the markings and instructions supplied with the module, contact the module supplier's technical support

9.2 Product Regulatory Compliance

9.2.1 Product Safety Compliance

The SR2100 complies with the following safety requirements:

- UL 1950 - CSA 950 (US/Canada)
- EN 60 950 (European Union)
- IEC60 950 (International)
- CE – Low Voltage Directive (73/23/EEC) (European Union)
- EMKO-TSE (74-SEC) 207/94 (Nordics)
- GOST R 50377-92 (Russia)
- IRAM (Argentina)

9.2.2 Product EMC Compliance

The SR2100 has been tested and verified to comply with the following Electromagnetic Compatibility (EMC) Regulations.

NOTE: The chassis kit, as shipped, has been tested and has passed product regulation EMI emissions testing with configurations using each of the supported server boards and added peripherals. Depending on the server integrators final system configuration, additional EMI gasketing may be required to maintain EMI regulatory requirements. It is the responsibility of the server integrator to validate that their final server configuration maintains compliance to regulatory requirements for the environment in which the server is intended.

- FCC (Class A Verification) – Radiated & Conducted Emissions (USA)
- ICES-003 (Class A) – Radiated & Conducted Emissions (Canada)
- CISPR 22 (Class A) – Radiated & Conducted Emissions (International)
- EN55022 (Class A) – Radiated & Conducted Emissions (European Union)
- EN55024 (Immunity) (European Union)
- EN61000-3-2 (Power Harmonics) (European Union) Fluctuation and Flicker
- EN61000-3-2 (Voltage Fluctuation and Flicker) (European Union)
- CE – EMC Directive (89/336/EEC) (European Union)
- VCCI (Class A) – Radiated & Conducted Emissions (Japan)
- AS/NZS 3548 (Class A) – Radiated & Conducted Emissions (AU/NZ)
- RRL–MIC Notices No. 1997-41 / 1997-42 (Class A) Radiated & Conducted Emissions (Korea)
- BSMI (CNS13438 - Class A) Radiated & Conducted Emissions (Taiwan)
- GOST R 29216-91 (Class A) Radiated & Conducted Emissions (Russia)
- GOST R 50628-95 (Immunity) (Russia)

9.2.3 Product Regulatory Compliance Markings

This product is provided with the following Product Certification Markings.

Table 15. Product Certification Markings

cULus Listing Marks	
German GS Mark	
CE Mark	
FCC/ICES-003 Marking (Class A)	This device complies with Part 15 of the FCC Rules. Operation of this device is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) This device must accept any interference received, including interference that may cause undesired operation. This Class A digital apparatus complies with Canadian ICES-003. Cet apprell numérique de la classe A este conforme à la norme NMB-003 du Canada. Manufactured by Intel Corporation.
Japan VCCI Marking (Class A)	この装置は、クラス A 情報技術装置です。この装置を家庭環境で使用すると電波妨害を引き起こすことがあります。この場合には使用者が適切な対策を講ずるよう要求されることがあります。VCCI-A
Australia C-Tick Mark	
Taiwan BSMI Marking (Class A)	警告使用者： 這是甲類的資訊產品，在居住的環境中使用時，可能會造成射頻干擾，在這種情況下，使用者會被要求採取某些適當的對策。
Russia GOST R Marking	
Model Name	SR2100

9.2.4 EMC Regulatory Compliance Notification Information

USA - FCC

FCC Verification Notice

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

For questions related to the EMC performance of this product, contact:

Intel Corporation
5200 N.E. Elam Young Parkway
Hillsboro, OR 97124
1-800-628-8686

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and the receiver.
- Connect the equipment to an outlet on a circuit other than the one to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

Any changes or modifications not expressly approved by the grantee of this device could void the user's authority to operate the equipment. The customer is responsible for ensuring compliance of the modified product.

Only peripherals (computer input/output devices, terminals, printers, etc.) that comply with FCC Class A or B limits may be attached to this computer product. Operation with noncompliant peripherals is likely to result in interference to radio and TV reception.

All cables used to connect to peripherals must be shielded and grounded. Operation with cables, connected to peripherals that are not shielded and grounded may result in interference to radio and TV reception.

CANADA – INDUSTRY CANADA

Cet appareil numérique respecte les limites bruits radioélectriques applicables aux appareils numériques de Classe A prescrites dans la norme sur le matériel brouilleur: "Appareils Numériques", NMB-003 édictée par le Ministre Canadian des Communications.

(English translation of the notice above) This digital apparatus does not exceed the Class A limits for radio noise emissions from digital apparatus set out in the interference-causing equipment standard entitled "Digital Apparatus," ICES-003 of the Canadian Department of Communications.

EUROPE (CE Declaration of Conformity)

This product has been tested in accordance too, and complies with the Low Voltage Directive (73/23/EEC) and EMC Directive (89/336/EEC). The product has been marked with the CE Mark to illustrate its compliance.

JAPAN – VCCI

この装置は、情報処理装置等電波障害自主規制協議会（ＶＣＣＩ）の基準に基づくクラスＡ情報技術装置です。この装置を家庭環境で使用すると電波妨害を引き起こすことがあります。この場合には使用者が適切な対策を講ずるよう要求されることがあります。

English translation of the notice above: This is a Class A product based on the standard of the Voluntary Control Council For Interference (VCCI) from Information Technology Equipment. If this is used near a radio or television receiver in a domestic environment, it may cause radio interference. Install and use the equipment according to the instruction manual.

ASIA-PACIFIC

TAIWAN - BSMI

The BSMI Certification ID number 3892I940 is located on the back chassis panel. The BSMI Class A EMC Warning label is located back chassis panel.

警告使用者：

這是甲類的資訊產品，在居住的環境中使用時，可能會造成射頻干擾，在這種情況下，使用者會被要求採取某些適當的對策。

10. Environmental Limits

10.1 System Office Environment

Table 16. System Office Environment Summary

Parameter	Limits
Operating Temperature	+5 °C to +35 °C with the maximum rate of change not to exceed 10 °C per hour.
Non-Operating Temperature	-40 °C to +70 °C
Non-Operating Humidity	95 %, non-condensing @ 30 °C
Acoustic noise	50 dBA in an idle state at typical office ambient temperature (65-75 °F)
Operating Shock	No errors with a half sine wave shock of 2 G (with 11 millisecond duration).
Package Shock	Operational after a 24-inch free fall, although cosmetic damage may be present
ESD	20 kV per Intel® Environmental test specification
System Cooling Requirement in BTU/Hr	1676 BTU/hour

10.2 System Environmental Testing

The system will be tested per the *Environmental Standards Handbook*, Intel® Doc.#662394-03. These tests shall include:

- Temperature Operating and Non-Operating
- Humidity Non-Operating
- Packaged and Unpackaged Shock
- Packaged and Unpackaged Vibration
- AC Voltage, Frequency and Source Interrupt
- AC Surge
- Acoustics
- ESD
- EMC Radiated Investigation

11. Serviceability and Availability

11.1 Serviceability

The system is designed to be serviced by qualified technical personnel only.

The desired Mean Time To Repair (MTTR) of the system is 35 minutes including diagnosis of the system problem. To meet this goal, the system enclosure and hardware have been designed to minimize the MTTR.

Following are the maximum times that a trained field service technician should take to perform the listed system maintenance procedures, after diagnosis of the system.

Table 17. Maintenance Procedures - Maximum Time Limit

Procedure	Time Limit
Remove cover	1 minute
Remove and replace hard disk drive	1 minute
Remove and replace peripheral device	5 minutes
Remove and replace power supply	10 minutes
Remove and replace front system fan	5 minutes
Remove and replace expansion board	5 minutes
Remove and replace front panel board	5 minutes
Remove and replace baseboard (with no expansion boards)	10 minutes
Overall MTTR	25 minutes

11.2 Calculated MTBF

The MTBF (Mean Time Between Failures) for the Intel® SR2100 Server Chassis as configured from the factory is calculated at 42,110 hours operating at 35 °C.

The table below shows the estimated MTBF calculations for three additional typical configurations with the Intel® SR2100 chassis.

Table 18. Estimated MTBF Calculated Values for SR2100

Baseboard	Power Supply Configuration	Total Failure Rate (FITs)	MTBF Hours
None	1+0	23,747	42,110
None	1+1	18,205	54,929
STL2	1+0	30,859	32,405
STL2	1+1	25,317	39,499

The following table shows the MTBF numbers for individual components within the SR2100 chassis.

Table 19. SR2100 Component MTBF Numbers

Sub Assembly Description	Sub Assy	Sub Assy MTBF Quote	Assy Temp Quote	Sub Assy Duty Cycle Quote	Duty Cycle as used in Sys	Sub Assy Temp in Sys	Total Sub Assy MTBF	Total Sub Assy Failure Rate
	QTY	(hrs)	(C)	(%)	(%)	(C)	(hrs)	(FITs)
Intel® STL2 Server Board	1	298,000	25	100	100	40	140,614	7,112
Front panel board	1	11,734,747	25	100	100	40	5,537,162	181
Processor	0	1,000,000	55	100	100	N/A	N/A	N/A
Processor terminator	0	13,819,790	25	100	100	N/A	N/A	N/A
SCSI Backplane Board	1	248,836	25	100	100	40	117,416	8,517
PCI Riser	1	7,644,250	25	100	100	46.9	2,608,324	383
IDE CD-ROM	1	75,000	25	20	5	36.3	N/A	N/A
Seagate Hard Drive	0	1,000,000	55	100	100	N/A	N/A	N/A
PRO 100 NIC	0	464,382	55	100	100	N/A	N/A	N/A
Power supply (1+0)	1	184,900	25	100	100	40	87,247	11,462
Power supply (1+1)	1	358,000	25	100	100	40	168,926	5,920
1.44-MB 3.5" FDU	0	81,000	35	5	1	N/A	N/A	N/A
32-MB DIMM (typ)	0	1,358,496	55	100	100	N/A	N/A	N/A
Fan (typ)	2	612,184	40	100	100	39.6	312,022	3,205

Note: Maximum Operating Temperature = 35 °C.

Appendix A: Glossary

Word / Acronym	Definition
AC	Alternating Current
ACPI	Advanced Configuration and Power Interface
ATX	Advanced Technology Extended (motherboard type)
BIOS	Basic Input/Output System
BMC	Baseboard Management Controller
DIMM	Dual In-Line Memory Module
ECC	Error Correction Code
EEPROM	Electrically Erasable Programmable Read Only Memory
EMI	Electromagnetic Interference
ESD	Electrostatic Discharge
FC-PGA	Flip Chip Pin Grid Array
FLASH	Memory Type
FRU	Field Replaceable Unit
HSBP	Hot-Swap Back Plane
IDE	Integrated Device Electronics
IMB	Intelligent Management Bus
ITE	Information Technology Equipment
LED	Light Emitting Diode
LVD	Low Voltage Differential
MTBF	Mean Time Between Failures
MTTR	Mean Time To Repair
NIC	Network Interface Card
NMI	Non-Maskable Interrupt
PCI	Peripheral Component Interconnect
PFC	Power Factor Correction
POST	Power On Self Test
RAID	Redundant Array of Independent Disks
SAF-TE	SCSI Accessed Fault-Tolerant Enclose specification
SCA	Single Connector Attachment
SCSI	Small Computer Systems Interface
SDRAM	Synchronous Dynamic Random Access Memory
SE	Single Ended
SGRAM	Synchronous Graphics RAM
SSI	Server System Infrastructure
TPS	Thin Power Supply
USB	Universal Serial Bus
VRM	Voltage Regulating Module
WOL	Wake On LAN

Appendix B: Reference Documents

Refer to the following documents for additional information:

- *Environmental Standards Handbook*, Intel® Doc.#662394-03
- *SCSI-Accessed Fault-Tolerant Enclosure Specification (SAF-TE)*
- *Intel® STL2 Server Board Technical Product Specification*